

## LM60-Q1 2.7V、SOT-23 温度传感器

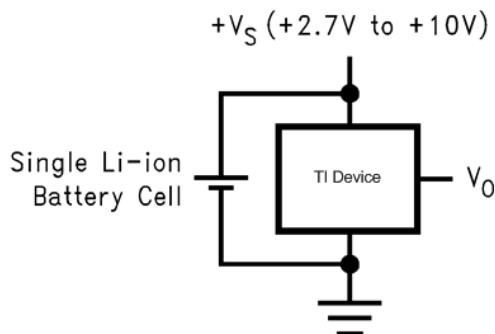
### 1 特性

- 符合 AEC-Q100 标准的汽车 标准
  - 器件温度等级 1: 环境工作温度范围为  $-40^{\circ}\text{C}$  至  $+125^{\circ}\text{C}$
  - 器件 HBM ESD 分类等级 2
- 校准后的线性比例因子为  $6.25\text{mV}/^{\circ}\text{C}$
- 额定温度范围为  $-40^{\circ}\text{C}$  至  $+125^{\circ}\text{C}$
- 适用于远程 应用
- 采用 SOT-23 封装
- 主要技术规格
  - $25^{\circ}\text{C}$  时的精度:  $\pm 2^{\circ}\text{C}$  和  $\pm 3^{\circ}\text{C}$  (最大值)
  - $-40^{\circ}\text{C}$  至  $+125^{\circ}\text{C}$  时的精度:  $\pm 4^{\circ}\text{C}$  (最大值)
  - $-25^{\circ}\text{C}$  至  $+125^{\circ}\text{C}$  时的精度:  $\pm 3^{\circ}\text{C}$  (最大值)
  - 温度斜率:  $6.25\text{mV}/^{\circ}\text{C}$
  - 电源电压范围:  $2.7\text{V}$  至  $10\text{V}$
  - $25^{\circ}\text{C}$  时的电流消耗:  $110\mu\text{A}$  (最大值)
  - 非线性:  $\pm 0.8^{\circ}\text{C}$  (最大值)
  - 输出阻抗:  $800\Omega$  (最大值)

### 2 应用

- 汽车
- 手机和计算机
- 电源模块
- 电池管理
- 传真机和打印机
- HVAC 和磁盘驱动器
- 电器

简化电路原理图



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### 3 说明

LM60-Q1 器件是一种精密集成电路温度传感器，可由  $2.7\text{V}$  单电源供电，并可检测  $-40^{\circ}\text{C}$  至  $+125^{\circ}\text{C}$  的温度范围。此器件的输出电压与摄氏温度成正比 ( $6.25\text{mV}/^{\circ}\text{C}$ )，并具有  $424\text{mV}$  的

直流失调电压。凭借此失调电压，在无需负电源的情况下即可读取负温度值。对于  $-40^{\circ}\text{C}$  至  $+125^{\circ}\text{C}$  的温度范围，此器件的标称输出电压范围介于  $174\text{mV}$  至  $1205\text{mV}$  之间。此器件经校准后可在室温下提供  $\pm 2^{\circ}\text{C}$  的精度，而在  $-25^{\circ}\text{C}$  至  $+125^{\circ}\text{C}$  的完整温度范围内提供  $\pm 3^{\circ}\text{C}$  的精度。

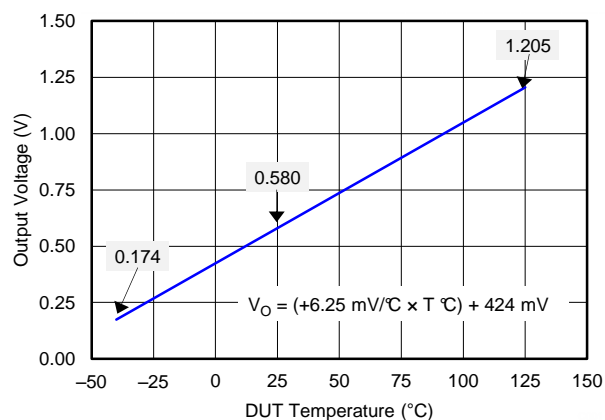
此器件的线性输出、 $+424\text{mV}$  失调电压和出厂校准简化了要求读取负温度值的单电源环境中所需要的外部电路。因为此器件的静态电流小于  $110\mu\text{A}$ ，所以在 SOT-23 封装中的静止空气中，自热限制在非常低的  $0.1^{\circ}\text{C}$ 。此器件本身便具备关断功能，这是因为其自身功耗低，因此可直接通过许多逻辑门的输出供电。

器件信息(1)

器件型号	封装	封装尺寸 (标称值)
LM60-Q1	SOT-23 (3)	2.92mm x 1.30mm

(1) 如需了解所有可用封装，请参阅数据表末尾的可订购产品附录。

全范围摄氏温度传感器  
( $-40^{\circ}\text{C}$  至  $+125^{\circ}\text{C}$ )



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## 4 修订历史记录

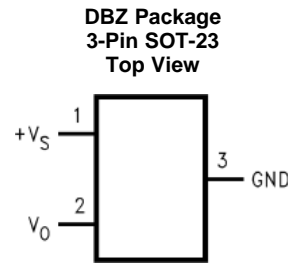
注：之前版本的页码可能与当前版本有所不同。

日期	修订版本	说明
2017 年 8 月	*	初始发行版。将 SNIS119 中的汽车器件移到了单独的数据表中

## 5 Device Comparison Table

ORDER NUMBER	ACCURACY OVER SPECIFIED TEMPERATURE RANGE	SPECIFIED TEMPERATURE RANGE
LM60BIM3	±3	–25°C ≤ T <sub>A</sub> ≤ +125°C
LM60BIM3X		
LM60CIM3	±4	–40°C ≤ T <sub>A</sub> ≤ +125°C
LM60CIM3X		
LM60QIM3	±4	–40°C ≤ T <sub>A</sub> ≤ +125°C
LM60QIM3X		
LM60BIZ	±3	–25°C ≤ T <sub>A</sub> ≤ +125°C
LM60CIZ	±4	–40°C ≤ T <sub>A</sub> ≤ +125°C

## 6 Pin Configuration and Functions



### Pin Functions

PIN		TYPE	DESCRIPTION
NAME	SOT-23		
GND	3	GND	Device ground, connected to power supply negative terminal
V <sub>OUT</sub>	2	O	Temperature sensor analog output
+V <sub>S</sub>	1	POWER	Positive power supply pin

## 7 Specifications

### 7.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)<sup>(1)</sup>

	MIN	MAX	UNIT
Supply voltage	-0.2	12	V
Output voltage	-0.6	V <sub>S</sub> + 0.6	V
Output current		10	mA
Input current at any pin <sup>(2)</sup>		5	mA
Maximum junction temperature (T <sub>JMAX</sub> )		125	°C
Storage temperature (T <sub>stg</sub> )	-65	150	°C

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) When the input voltage (V<sub>I</sub>) at any pin exceeds power supplies (V<sub>I</sub> < GND or V<sub>I</sub> > +V<sub>S</sub>), the current at that pin should be limited to 5 mA.

### 7.2 ESD Ratings

		VALUE	UNIT
V <sub>(ESD)</sub>	Electrostatic discharge <sup>(1)</sup>	Human-body model (HBM), per AEC Q100-002 <sup>(2)</sup>	±2500
		Machine model (MM)	±250

- (1) The human body model is a 100-pF capacitor discharged through a 1.5-kΩ resistor into each pin. The machine model is a 200-pF capacitor discharged directly into each pin.
- (2) AEC Q100-002 indicates that HBM stressing shall be in accordance with the ANSI/ESDA/JEDEC JS-001 specification.

### 7.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)<sup>(1)</sup>

	MIN	MAX	UNIT
LM60-Q1 ( $T_{MIN} \leq T_A \leq T_{MAX}$ )	-40	125	°C
Supply voltage (+V <sub>S</sub> )	2.7	10	V

(1) Soldering process must comply with National Semiconductor's Reflow Temperature Profile specifications. Refer to [www.national.com/packaging](http://www.national.com/packaging). Reflow temperature profiles are different for lead-free and non-lead-free packages.

### 7.4 Thermal Information

THERMAL METRIC <sup>(1)</sup>		LM60-Q1	UNIT
		DBZ (SOT-23)	
		3 PINS	
R <sub>θJA</sub> <sup>(2)</sup>	Junction-to-ambient thermal resistance	266	°C/W
R <sub>θJC(top)</sub>	Junction-to-case (top) thermal resistance	135	°C/W
R <sub>θJB</sub>	Junction-to-board thermal resistance	59	°C/W
ψ <sub>JT</sub>	Junction-to-top characterization parameter	18	°C/W
ψ <sub>JB</sub>	Junction-to-board characterization parameter	58	°C/W

(1) For more information about traditional and new thermal metrics, see the [Semiconductor or IC Package Thermal Metrics](#) application report.

(2) The junction to ambient thermal resistance (R<sub>θJA</sub>) is specified without a heat sink in still air.

### 7.5 Electrical Characteristics

Unless otherwise noted, these specifications apply for +V<sub>S</sub> = 3 V<sub>DC</sub> and I<sub>LOAD</sub> = 1 μA. All limits T<sub>A</sub> = T<sub>J</sub> = 25°C unless otherwise noted.

PARAMETER	TEST CONDITIONS		MIN <sup>(1)</sup>	TYP <sup>(2)</sup>	MAX <sup>(1)</sup>	UNIT
Accuracy <sup>(3)</sup>	LM60-Q1		-3		3	°C
		T <sub>A</sub> = T <sub>J</sub> = T <sub>MIN</sub> to T <sub>MAX</sub>	-4		4	
Output voltage at 0°C				424		mV
Nonlinearity <sup>(4)</sup>	LM60-Q1	T <sub>A</sub> = T <sub>J</sub> = T <sub>MIN</sub> to T <sub>MAX</sub>	-0.8		±0.8	°C
Sensor gain (average slope)	LM60-Q1	T <sub>A</sub> = T <sub>J</sub> = T <sub>MIN</sub> to T <sub>MAX</sub>	6		6.5	mV/°C
Output impedance	T <sub>A</sub> = T <sub>J</sub> = T <sub>MIN</sub> to T <sub>MAX</sub>				800	Ω
Line regulation <sup>(5)</sup>	3 V ≤ +V <sub>S</sub> ≤ 10 V	T <sub>A</sub> = T <sub>J</sub> = T <sub>MIN</sub> to T <sub>MAX</sub>	-0.3		0.3	mV/V
	2.7 V ≤ +V <sub>S</sub> ≤ 3.3 V	T <sub>A</sub> = T <sub>J</sub> = T <sub>MIN</sub> to T <sub>MAX</sub>	-2.3		2.3	mV
Quiescent current	2.7 V ≤ +V <sub>S</sub> ≤ 10 V			82	110	μA
		T <sub>A</sub> = T <sub>J</sub> = T <sub>MIN</sub> to T <sub>MAX</sub>			125	
Change of quiescent current	2.7 V ≤ +V <sub>S</sub> ≤ 10 V			±5		μA
Temperature coefficient of quiescent current				0.2		μA/°C

(1) Limits are specified to TI's AOQL (Average Outgoing Quality Level).

(2) Typicals are at T<sub>J</sub> = T<sub>A</sub> = 25°C and represent most likely parametric norm.

(3) Accuracy is defined as the error between the output voltage and 6.25 mV/°C times the case temperature of the device plus 424 mV, at specified conditions of voltage, current, and temperature (expressed in °C).

(4) Nonlinearity is defined as the deviation of the output-voltage-versus-temperature curve from the best-fit straight line, over the rated temperature range of the device.

(5) Regulation is measured at constant junction temperature, using pulse testing with a low duty cycle. Changes in output due to heating effects can be computed by multiplying the internal dissipation by the thermal resistance.

**Electrical Characteristics (continued)**

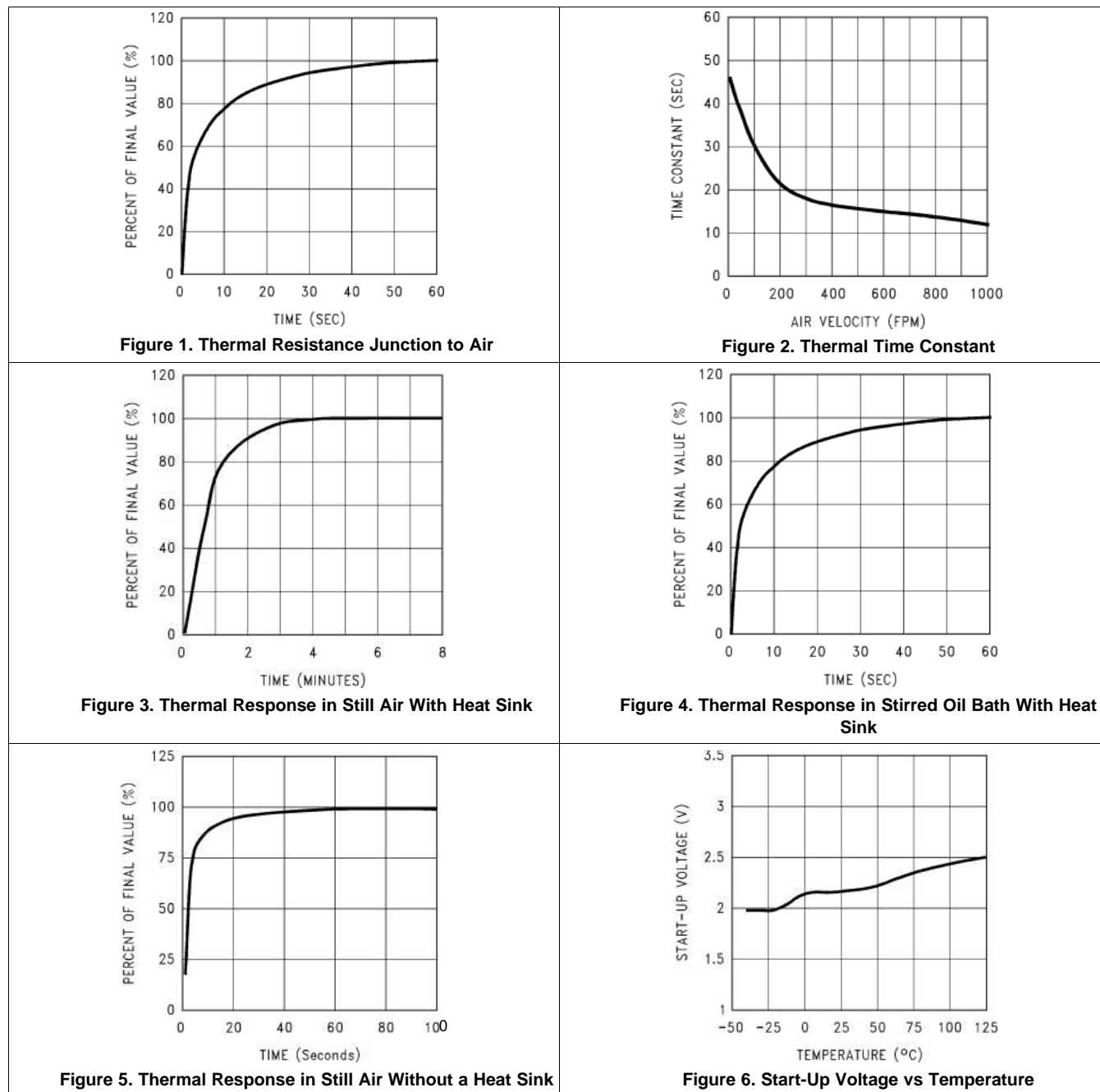
Unless otherwise noted, these specifications apply for  $+V_S = 3 V_{DC}$  and  $I_{LOAD} = 1 \mu A$ . All limits  $T_A = T_J = 25^\circ C$  unless otherwise noted.

PARAMETER	TEST CONDITIONS	MIN <sup>(1)</sup>	TYP <sup>(2)</sup>	MAX <sup>(1)</sup>	UNIT
Long-term stability <sup>(6)</sup>	$T_J = T_{MAX} = 125^\circ C$ for 1000 hours		$\pm 0.2$		$^\circ C$

- (6) For best long-term stability, any precision circuit will give best results if the unit is aged at a warm temperature, temperature cycled for at least 46 hours before long-term life test begins for both temperatures. This is especially true when a small (surface-mount) part is wave-soldered; allow time for stress relaxation to occur. The majority of the drift will occur in the first 1000 hours at elevated temperatures. The drift after 1000 hours will not continue at the first 1000 hour rate.

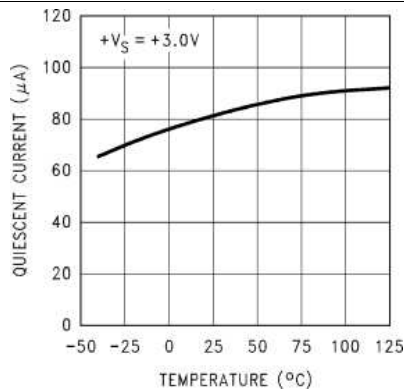
## 7.6 Typical Characteristics

To generate these curves, the device was mounted to a printed-circuit board as shown in [Figure 20](#).

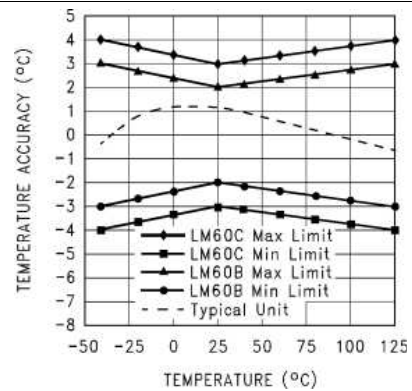


**Typical Characteristics (continued)**

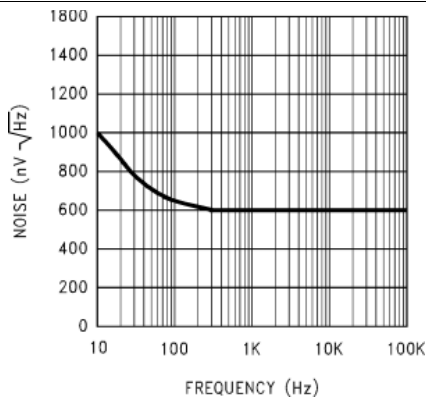
To generate these curves, the device was mounted to a printed-circuit board as shown in Figure 20.



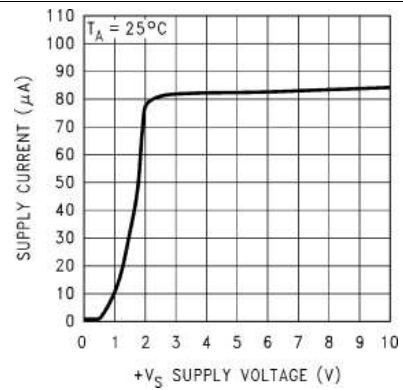
**Figure 7. Quiescent Current vs Temperature**



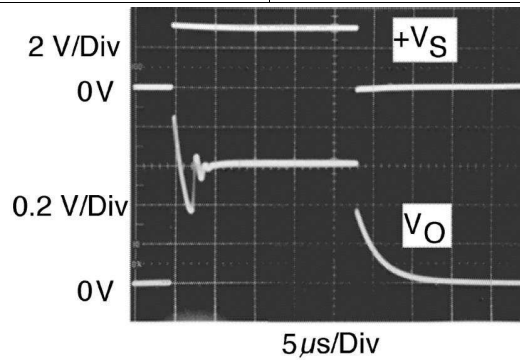
**Figure 8. Accuracy vs Temperature**



**Figure 9. Noise Voltage**



**Figure 10. Supply Voltage vs Supply Current**



**Figure 11. Start-Up Response**

SVA-1268122



## 8 Detailed Description

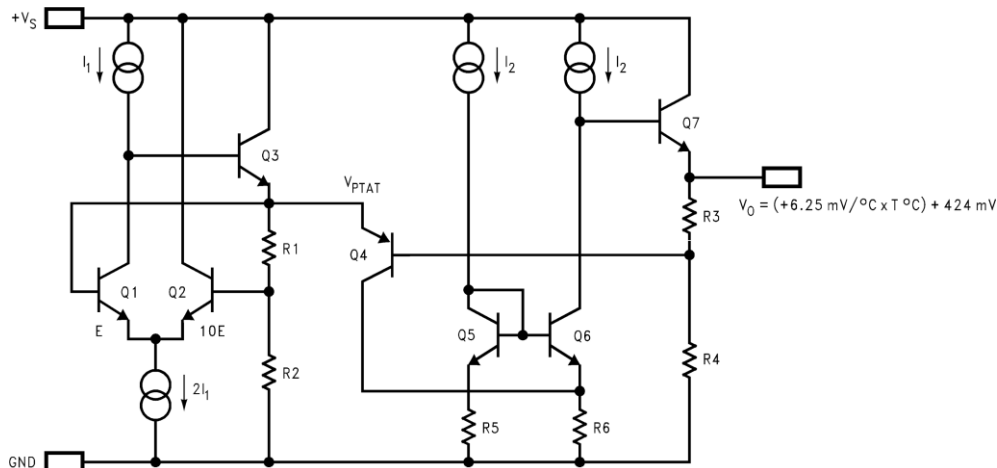
### 8.1 Overview

The LM60-Q1 devices are precision analog bipolar temperature sensors that can sense a  $-40^{\circ}\text{C}$  to  $+125^{\circ}\text{C}$  temperature range while operating from a single 2.7-V supply. The output voltage of the LM60-Q1 is linearly proportional to Celsius (Centigrade) temperature ( $6.25\text{ mV}/^{\circ}\text{C}$ ) and has a DC offset of 424 mV. The offset allows reading negative temperatures with a single positive supply. The nominal output voltage of the device ranges from 174 mV to 1205 mV for a  $-40^{\circ}\text{C}$  to  $+125^{\circ}\text{C}$  temperature range. The device is calibrated to provide accuracies of  $\pm 2.0^{\circ}\text{C}$  at room temperature and  $\pm 3^{\circ}\text{C}$  over the full  $-25^{\circ}\text{C}$  to  $+125^{\circ}\text{C}$  temperature range.

With a quiescent current of the device is less than  $110\text{ }\mu\text{A}$ , self-heating is limited to a very low  $0.1^{\circ}\text{C}$  in still air in the SOT-23 package. Shutdown capability for the device is intrinsic because its inherent low power consumption allows it to be powered directly from the output of many logic gates.

The output of the LM60-Q1 is a Class A base emitter follower, thus the LM60-Q1 can source quite a bit of current while sinking less than  $1\text{ }\mu\text{A}$ . In any event load current should be minimized in order to limit its contribution to the total temperature error. The temperature-sensing element is based on a delta  $V_{\text{BE}}$  topology of two transistors (Q1 and Q2 in [Functional Block Diagram](#)) that are sized with a 10:1 area ratio.

### 8.2 Functional Block Diagram



### 8.3 Feature Description

#### 8.3.1 LM60 Transfer Function

The LM60 follows a simple linear transfer function to achieve the accuracy as listed in [Electrical Characteristics](#) as given:

$$V_o = (6.25\text{ mV}/^{\circ}\text{C} \times T\text{ }^{\circ}\text{C}) + 424\text{ mV}$$

where

- T is the temperature
- $V_o$  is the LM60-Q1 output voltage

(1)

### 8.4 Device Functional Modes

The only functional mode for this device is an analog output directly proportional to temperature.

## 9 Application and Implementation

### NOTE

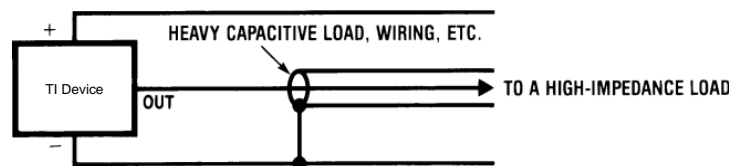
Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

### 9.1 Application Information

The device has a low supply current and a wide supply range, therefore it can easily be driven by a battery.

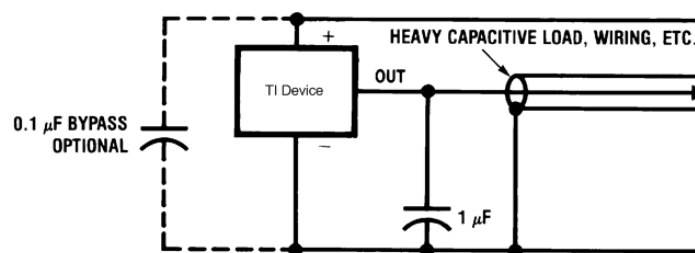
#### 9.1.1 Capacitive Loads

The device handles capacitive loading well. Without any special precautions, the device can drive any capacitive load as shown in Figure 12. Over the specified temperature range the device has a maximum output impedance of 800  $\Omega$ . In an extremely noisy environment, adding some filtering to minimize noise pick-up may be required. TI recommends that 0.1  $\mu\text{F}$  be added from +V<sub>S</sub> to GND to bypass the power supply voltage, as shown in Figure 13. In a noisy environment, adding a capacitor from the output to ground may be required. A 1- $\mu\text{F}$  output capacitor with the 800- $\Omega$  output impedance forms a 199-Hz, low-pass filter. Because the thermal time constant of the device is much slower than the 6.3-ms time constant formed by the RC, the overall response time of the device is not be significantly affected. For much larger capacitors, this additional time lag increases the overall response time of the device.



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Figure 12. No Decoupling Required for Capacitive Load



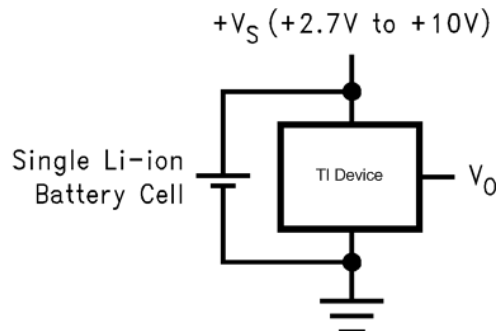
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Figure 13. Filter Added for Noisy Environment

## 9.2 Typical Applications

### 9.2.1 Full-Range Centigrade Temperature Sensor

Because the LM60-Q1 is a simple temperature sensor that provides an analog output, design requirements related to the layout are also important. Refer to [Layout](#) for details.



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$$V_O = (6.25 \text{ mV/}^\circ\text{C} \times T^\circ\text{C}) + 424 \text{ mV}$$

**Figure 14. Full-Range Centigrade Temperature Sensor (–40°C to +125°C) Operating From a Single Li-Ion Battery Cell**

#### 9.2.1.1 Design Requirements

For this design example, use the design parameters listed in [Table 1](#).

**Table 1. Temperature and Typical  $V_O$  Values of [Figure 14](#)**

TEMPERATURE (T)	TYPICAL $V_O$
125°C	1205 mV
100°C	1049 mV
25°C	580 mV
0°C	424 mV
–25°C	268 mV
–40°C	174 mV

### 9.2.1.2 Detailed Design Procedure

Selection of the LM60-Q1 is based on the output voltage transfer function being able to meet the needs of the rest of the system.

### 9.2.1.3 Application Curve

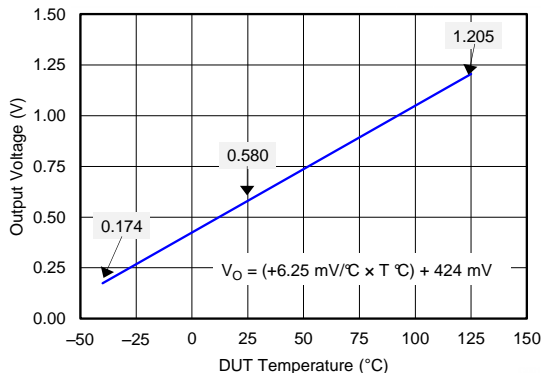
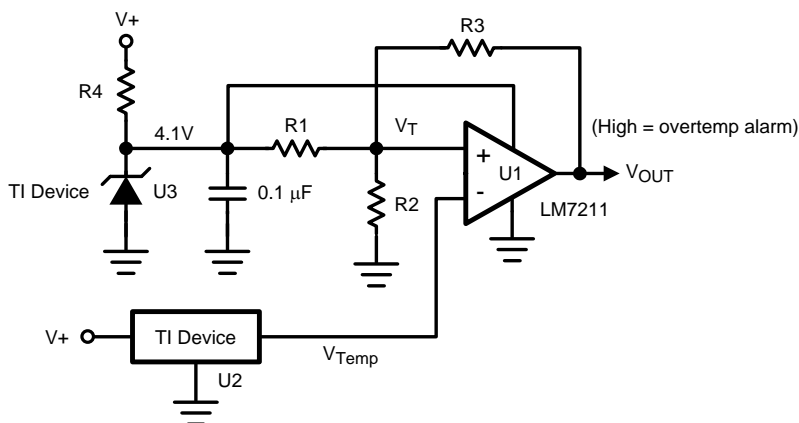


Figure 15. LM60-Q1 Output Transfer Function

## 9.2.2 Centigrade Thermostat Application



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Figure 16. Centigrade Thermostat

### 9.2.2.1 Design Requirements

A simple thermostat can be created by using a reference (LM4040) and a comparator (LM7211) as shown in Figure 16.

### 9.2.2.2 Detailed Design Procedure

Use Equation 2 and Equation 3 to calculate the threshold values for T1 and T2.

$$V_{T1} = \frac{(4.1)R2}{R2 + R1 || R3} \tag{2}$$

$$V_{T2} = \frac{(4.1)R2 || R3}{R1 + R2 || R3} \tag{3}$$

### 9.2.2.3 Application Curve

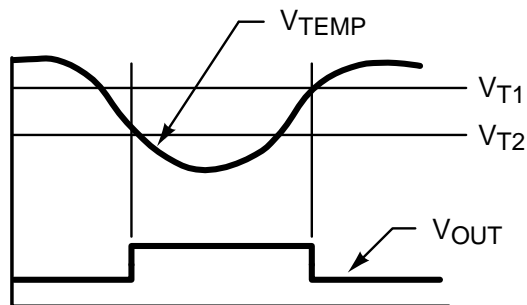
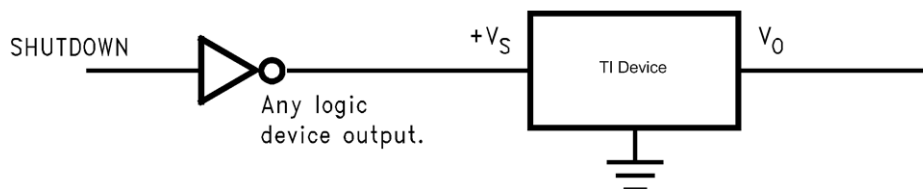


Figure 17. Thermostat Output Waveform

## 9.3 System Examples

### 9.3.1 Conserving Power Dissipation With Shutdown

The LM60-Q1 draws very little power, therefore it can simply be shutdown by driving the LM60-Q1 supply pin with the output of a logic gate as shown in Figure 18.



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Figure 18. Conserving Power Dissipation With Shutdown

## 10 Power Supply Recommendations

In an extremely noisy environment, add some filtering to minimize noise pick-up. Adding 0.1  $\mu\text{F}$  from  $+V_S$  to GND is recommended to bypass the power supply voltage, as shown in Figure 13. In a noisy environment, add a capacitor from the output to ground.

## 11 Layout

### 11.1 Layout Guidelines

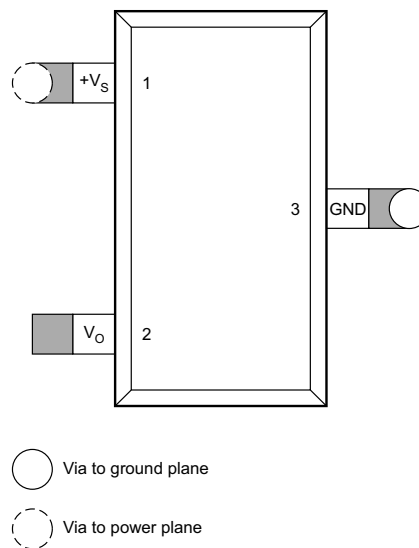
The LM60-Q1 can be applied easily in the same way as other integrated-circuit temperature sensors. It can be glued or cemented to a surface. The temperature that the LM60-Q1 is sensing will be within about +0.1°C of the surface temperature that the leads of the LM60-Q1 are attached to.

This presumes that the ambient air temperature is almost the same as the surface temperature. If the air temperature were much higher or lower than the surface temperature, the actual temperature of the device die would be at an intermediate temperature between the surface temperature and the air temperature.

To ensure good thermal conductivity the backside of the device die is directly attached to the GND pin. The lands and traces to the device will, of course, be part of the printed-circuit board, which is the object whose temperature is being measured. These printed-circuit board lands and traces do not cause the temperature of the device to deviate from the desired temperature.

Alternatively, the device can be mounted inside a sealed-end metal tube, and can then be dipped into a bath or screwed into a threaded hole in a tank. As with any IC, the device and accompanying wiring and circuits must be kept insulated and dry to avoid leakage and corrosion. Specifically when the device operates at cold temperatures where condensation can occur. Printed-circuit coatings and varnishes such as a conformal coating and epoxy paints or dips are often used to ensure that moisture cannot corrode the device or connections.

### 11.2 Layout Example



1/2-inch square printed circuit board with 2-oz. copper foil or similar.

**Figure 19. PCB Layout**

### 11.3 Thermal Considerations

The thermal resistance junction to ambient ( $R_{\theta JA}$ ) is the parameter used to calculate the rise of a device junction temperature due to the device power dissipation. Use [Equation 4](#) to calculate the rise in the die temperature of the device.

$$T_J = T_A + R_{\theta JA} [(+V_S I_Q) + (+V_S - V_O) I_L]$$

where

- $I_Q$  is the quiescent current
- $I_L$  is the load current on the output

(4)

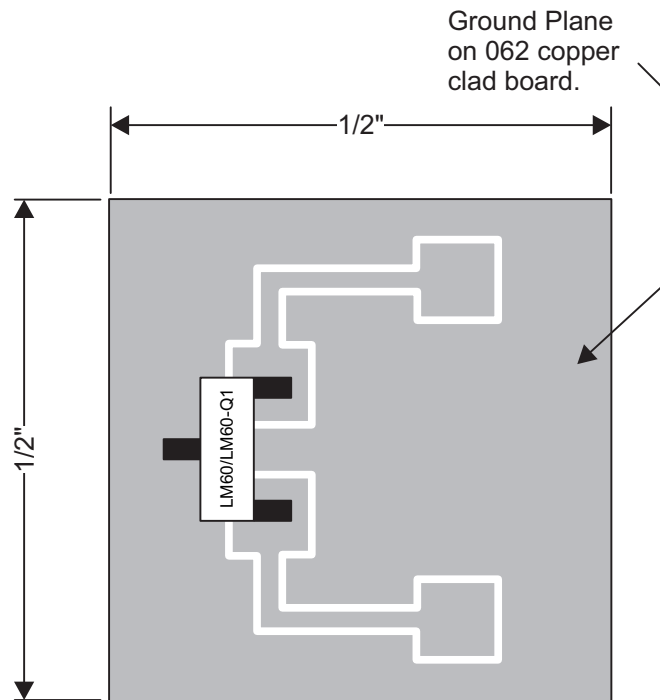
**Thermal Considerations (continued)**

Table 2 summarizes the rise in die temperature of the LM60-Q1 without any loading, and the thermal resistance for different conditions. The values in Table 2 were actually measured where as the values shown in where calculated using modeling methods as described in the *Semiconductor and IC Package Thermal Metrics* (SPRA953) application report.

**Table 2. Temperature Rise of LM60-Q1 Due to Self-Heating and Thermal Resistance ( $R_{\theta JA}$ )**

	SOT-23 <sup>(1)</sup> NO HEAT SINK		SOT-23 <sup>(2)</sup> SMALL HEAT FIN		TO-92 <sup>(1)</sup> NO HEAT FIN		TO-92 <sup>(3)</sup> SMALL HEAT FIN	
	$R_{\theta JA}$	$T_J - T_A$	$R_{\theta JA}$	$T_J - T_A$	$R_{\theta JA}$	$T_J - T_A$	$R_{\theta JA}$	$T_J - T_A$
	(°C/W)	(°C)	(°C/W)	(°C)	(°C/W)	(°C)	(°C/W)	(°C)
Still air	450	0.17	260	0.1	180	0.07	140	0.05
Moving air	—	—	180	0.07	90	0.034	70	0.026

- (1) Part soldered to 30 gauge wire.
- (2) Heat sink used is 1/2-in square printed-circuit board with 2-oz. foil with part attached as shown in Figure 20.
- (3) Part glued or leads soldered to 1-in square of 1/16-in printed-circuit board with 2-oz. foil or similar.



1/2-in Square Printed-Circuit Board with 2-oz. Copper Foil or Similar.

**Figure 20. Printed-Circuit Board Used for Heat Sink to Generate Thermal Response Curves**

## 12 器件和文档支持

### 12.1 接收文档更新通知

要接收文档更新通知，请转至 [TI.com](http://TI.com) 上的器件产品文件夹。单击右上角的 [通知我](#) 进行注册，即可每周接收产品信息更改摘要。有关更改的详细信息，请查看任何已修订文档中包含的修订历史记录。

### 12.2 社区资源

下列链接提供到 TI 社区资源的连接。链接的内容由各个分销商“按照原样”提供。这些内容并不构成 TI 技术规范，并且不一定反映 TI 的观点；请参阅 TI 的 [《使用条款》](#)。

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**设计支持** [TI 参考设计支持](#) 可帮助您快速查找有帮助的 E2E 论坛、设计支持工具以及技术支持的联系信息。

### 12.3 商标

E2E is a trademark of Texas Instruments.

All other trademarks are the property of their respective owners.

### 12.4 静电放电警告



这些装置包含有限的内置 ESD 保护。存储或装卸时，应将导线一起截短或将装置放置于导电泡棉中，以防止 MOS 门极遭受静电损伤。

### 12.5 Glossary

[SLYZ022](#) — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

## 13 机械、封装和可订购信息

以下页面包含机械、封装和可订购信息。这些信息是指定器件的最新可用数据。这些数据如有变更，恕不另行通知和修订此文档。如欲获取此数据表的浏览器版本，请参阅左侧的导航。



**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
LM60QIM3/NOPB	ACTIVE	SOT-23	DBZ	3	1000	RoHS & Green	SN	Level-1-260C-UNLIM	-40 to 125	L60Q	<b>Samples</b>
LM60QIM3X/NOPB	ACTIVE	SOT-23	DBZ	3	3000	RoHS & Green	SN	Level-1-260C-UNLIM	-40 to 125	L60Q	<b>Samples</b>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

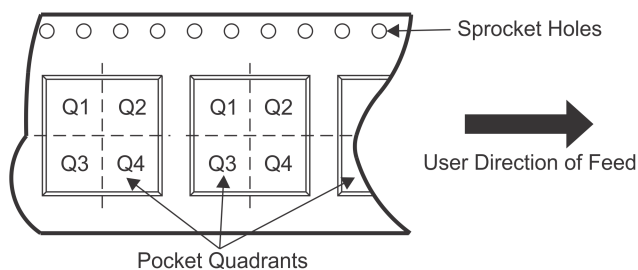
(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LM60QIM3/NOPB	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM60QIM3X/NOPB	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

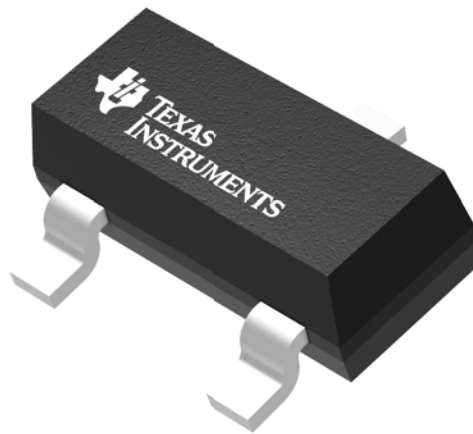
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LM60QIM3/NOPB	SOT-23	DBZ	3	1000	208.0	191.0	35.0
LM60QIM3X/NOPB	SOT-23	DBZ	3	3000	208.0	191.0	35.0

## GENERIC PACKAGE VIEW

**DBZ 3**

**SOT-23 - 1.12 mm max height**

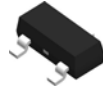
SMALL OUTLINE TRANSISTOR



Images above are just a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.

4203227/C

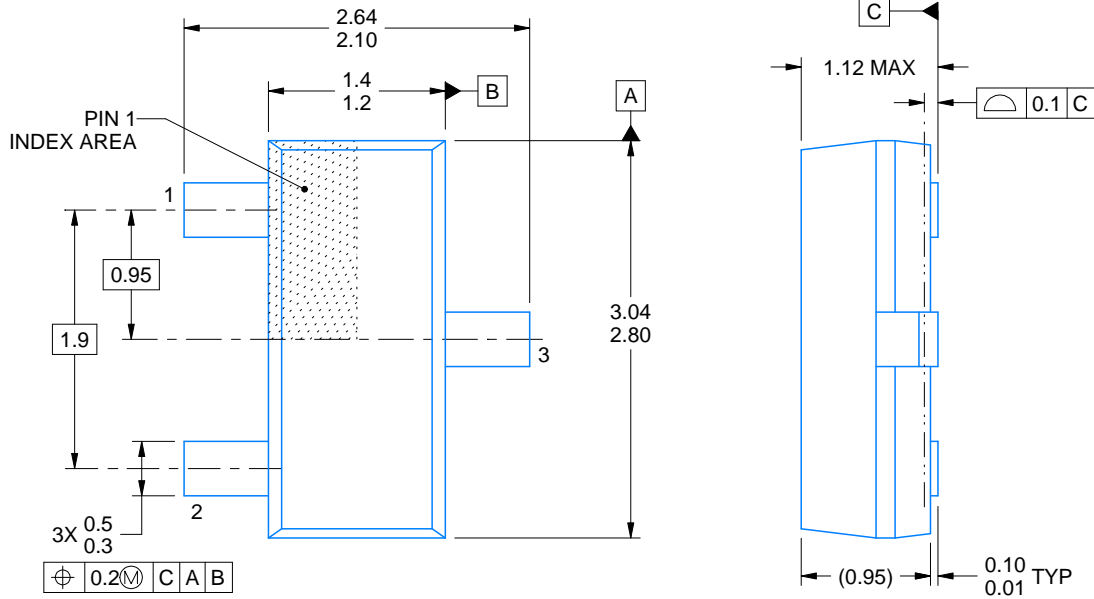
DBZ0003A



# PACKAGE OUTLINE

SOT-23 - 1.12 mm max height

SMALL OUTLINE TRANSISTOR



4214838/C 04/2017

NOTES:

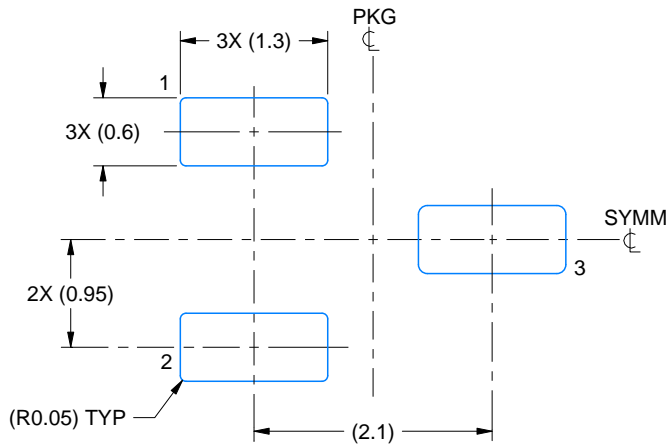
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Reference JEDEC registration TO-236, except minimum foot length.

# EXAMPLE BOARD LAYOUT

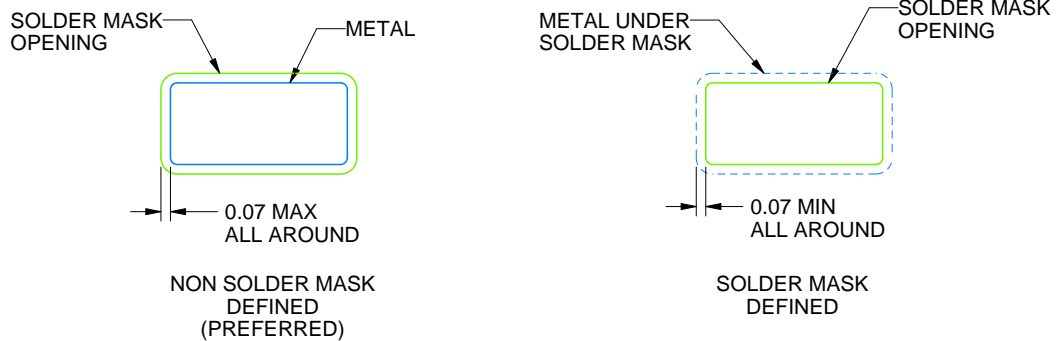
DBZ0003A

SOT-23 - 1.12 mm max height

SMALL OUTLINE TRANSISTOR



LAND PATTERN EXAMPLE  
SCALE:15X



SOLDER MASK DETAILS

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NOTES: (continued)

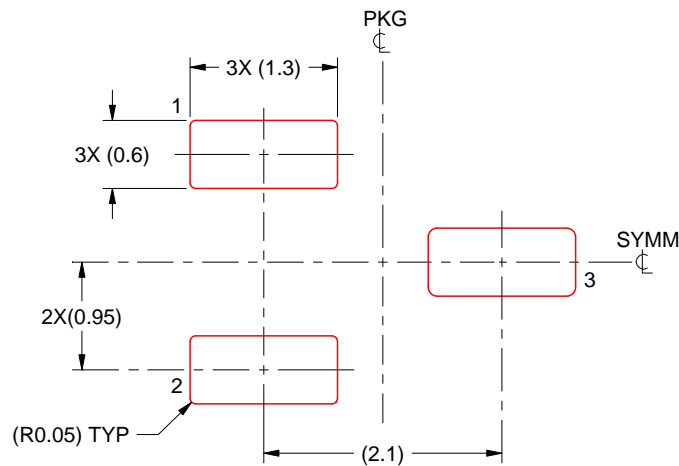
4. Publication IPC-7351 may have alternate designs.
5. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

DBZ0003A

SOT-23 - 1.12 mm max height

SMALL OUTLINE TRANSISTOR



SOLDER PASTE EXAMPLE  
BASED ON 0.125 THICK STENCIL  
SCALE:15X

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NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
7. Board assembly site may have different recommendations for stencil design.



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